



Material Content Data Sheet



Sales Product Name		BTS3205G		Issued		24. January 2018		
MA#		MA000384019						
Package		PG-DSO-8-24		Weight*		82.82 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.717	0.87	0.87	8656	8656
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		433	
	non noble metal	iron	7439-89-6	0.717	0.87		8660	
wire	non noble metal	copper	7440-50-8	29.121	35.16	36.08	351615	360816
	noble metal	gold	7440-57-5	0.243	0.29	0.29	2929	2929
	encapsulation	organic material	carbon black	1333-86-4	0.100	0.12		1211
encapsulation	plastics	epoxy resin	-	4.612	5.57		55691	
	inorganic material	silicondioxide	60676-86-0	45.422	54.84	60.53	548433	605335
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9826	9826
plating	noble metal	silver	7440-22-4	0.650	0.79	0.79	7851	7851
glue	plastics	epoxy resin	-	0.066	0.08		803	
	noble metal	silver	7440-22-4	0.313	0.38	0.46	3784	4587
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com